

International IR Rectifier

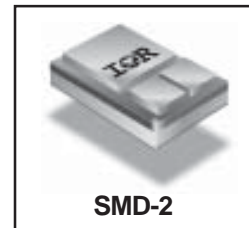
RADIATION HARDENED POWER MOSFET SURFACE-MOUNT (SMD-2)

PD - 94299

IRHNA67160
100V, N-CHANNEL
R₆ TECHNOLOGY

Product Summary

Part Number	Radiation Level	RDS(on)	Id
IRHNA67160	100K Rads (Si)	0.01Ω	75A*
IRHNA63160	300K Rads (Si)	0.01Ω	75A*
IRHNA64160	600K Rads (Si)	0.01Ω	75A*
IRHNA68160	1000K Rads (Si)	0.01Ω	75A*



International Rectifier's R6™ technology provides superior power MOSFETs for space applications. These devices have improved immunity to Single Event Effect (SEE) and have been characterized for useful performance with Linear Energy Transfer (LET) up to 90MeV/(mg/cm²).

Their combination of very low RDS(on) and faster switching times reduces power loss and increases power density in today's high speed switching applications such as DC-DC converters and motor controllers. These devices retain all of the well established advantages of MOSFETs such as voltage control, ease of paralleling and temperature stability of electrical parameters.

Features:

- Low RDS(on)
- Fast Switching
- Single Event Effect (SEE) Hardened
- Low Total Gate Charge
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Surface Mount
- Ceramic Package
- Light Weight

Absolute Maximum Ratings

Pre-Irradiation

	Parameter		Units
Id @ VGS = 12V, TC = 25°C	Continuous Drain Current	75*	A
Id @ VGS = 12V, TC = 100°C	Continuous Drain Current	72	
IDM	Pulsed Drain Current ①	300	
Pd @ TC = 25°C	Max. Power Dissipation	250	W
	Linear Derating Factor	2.0	W/°C
VGS	Gate-to-Source Voltage	±20	V
EAS	Single Pulse Avalanche Energy ②	360	mJ
IAR	Avalanche Current ①	75	A
EAR	Repetitive Avalanche Energy ①	25	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.0	V/ns
TJ	Operating Junction	-55 to 150	°C
TSTG	Storage Temperature Range		
	Pckg. Mounting Surface Temp.	300 (for 5s)	
	Weight	3.3 (Typical)	g

* Current is limited by package
For footnotes refer to the last page

www.irf.com

1

08/14/03

Electrical Characteristics @ T_j = 25°C (Unless Otherwise Specified)

	Parameter	Min	Typ	Max	Units	Test Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	100	—	—	V	V _{GS} = 0V, I _D = 1.0mA
ΔBV _{DSS} /ΔT _J	Temperature Coefficient of Breakdown Voltage	—	0.11	—	V/°C	Reference to 25°C, I _D = 1.0mA
R _{DS(on)}	Static Drain-to-Source On-State Resistance	—	—	0.01	Ω	V _{GS} = 12V, I _D = 72A ④
V _{GS(th)}	Gate Threshold Voltage	2.0	—	4.0	V	V _{DS} = V _{GS} , I _D = 1.0mA
g _{fs}	Forward Transconductance	60	—	—	S (⑦)	V _{DS} = 25V, I _{DS} = 72A ④
I _{DSS}	Zero Gate Voltage Drain Current	—	—	10	μA	V _{DS} = 80V, V _{GS} = 0V
		—	—	25		V _{DS} = 80V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Leakage Forward	—	—	100	nA	V _{GS} = 20V
I _{GSS}	Gate-to-Source Leakage Reverse	—	—	-100		V _{GS} = -20V
Q _g	Total Gate Charge	—	—	165	nC	V _{GS} = 12V, I _D = 75A V _{DS} = 50V
Q _{gs}	Gate-to-Source Charge	—	—	80		
Q _{gd}	Gate-to-Drain ('Miller') Charge	—	—	60		
t _{d(on)}	Turn-On Delay Time	—	—	35	ns	V _{DD} = 50V, I _D = 75A, V _{GS} = 12V, R _G = 2.35Ω
t _r	Rise Time	—	—	125		
t _{d(off)}	Turn-Off Delay Time	—	—	75		
t _f	Fall Time	—	—	20		
L _S + L _D	Total Inductance	—	2.8	—	nH	Measured from the center of drain pad to center of source pad
C _{iss}	Input Capacitance	—	8915	—	pF	V _{GS} = 0V, V _{DS} = 25V f = 100KHz
C _{oss}	Output Capacitance	—	1600	—		
C _{rss}	Reverse Transfer Capacitance	—	22.7	—		
R _g	Internal Gate Resistance	—	0.96	—		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min	Typ	Max	Units	Test Conditions
I _S	Continuous Source Current (Body Diode)	—	—	75*	A	T _j = 25°C, I _S = 75A, V _{GS} = 0V ④
I _{SM}	Pulse Source Current (Body Diode) ①	—	—	300		
V _{SD}	Diode Forward Voltage	—	—	1.2	V	T _j = 25°C, I _F = 75A, di/dt ≤ 100A/μs
t _{rr}	Reverse Recovery Time	—	—	500	ns	V _{DD} ≤ 25V ④
Q _{RR}	Reverse Recovery Charge	—	—	6.9	μC	
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L _S + L _D .				

* Current is limited by package

Thermal Resistance

	Parameter	Min	Typ	Max	Units	Test Conditions
R _{thJC}	Junction-to-Case	—	—	0.5	°C/W	

Note: Corresponding Spice and Saber models are available on International Rectifier Web site.

For footnotes refer to the last page

Radiation Characteristics

IRHNA67160

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

Table 1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation ⑤⑥

Parameter	Units	Up to 600K Rads(Si) ¹		1000K Rads (Si) ²		Test Conditions
		Min	Max	Min	Max	
BV _{DSS}	Drain-to-Source Breakdown Voltage	100	—	100	—	V V _{GS} = 0V, I _D = 1.0mA
V _{GS(th)}	Gate Threshold Voltage	2.0	4.0	1.5	4.0	V V _{GS} = V _{DS} , I _D = 1.0mA
I _{GSS}	Gate-to-Source Leakage Forward	—	100	—	100	nA V _{GS} = 20V
I _{GSS}	Gate-to-Source Leakage Reverse	—	-100	—	-100	nA V _{GS} = -20 V
I _{DSS}	Zero Gate Voltage Drain Current	—	10	—	25	μA V _{DS} = 80V, V _{GS} = 0V
R _{DS(on)}	Static Drain-to-Source On-State Resistance (TO-3)	—	0.011	—	0.011	Ω V _{GS} = 12V, I _D = 72A
R _{DS(on)}	Static Drain-to-Source On-State Resistance (SMD-2)	—	0.010	—	0.010	Ω V _{GS} = 12V, I _D = 72A
V _{SD}	Diode Forward Voltage ④	—	1.2	—	1.2	V V _{GS} = 0V, I _S = 75A

1. Part numbers IRHNA67160, IRHNA63160 and IRHNA64160
2. Part number IRHNA68160

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

Table 2. Single Event Effect Safe Operating Area

Ion	LET (MeV/(mg/cm ²))	Energy (MeV)	Range (μm)	VDS (V)						
				@VGS= 0V	@VGS= -5V	@VGS= -10V	@VGS= -15V	@VGS= -17V	@VGS= -19V	@VGS= -20V
Br	36.7	309	39.5	100	100	100	100	100	100	40
I	59.8	341	32.5	100	100	100	30	-	-	-
Au	82.3	350	28.4	100	100	-	-	-	-	-

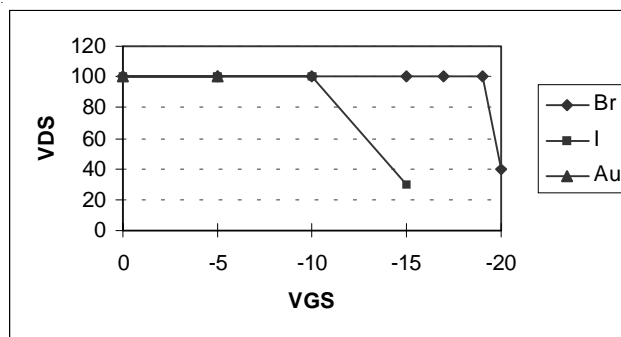


Fig a. Single Event Effect, Safe Operating Area

For footnotes refer to the last page

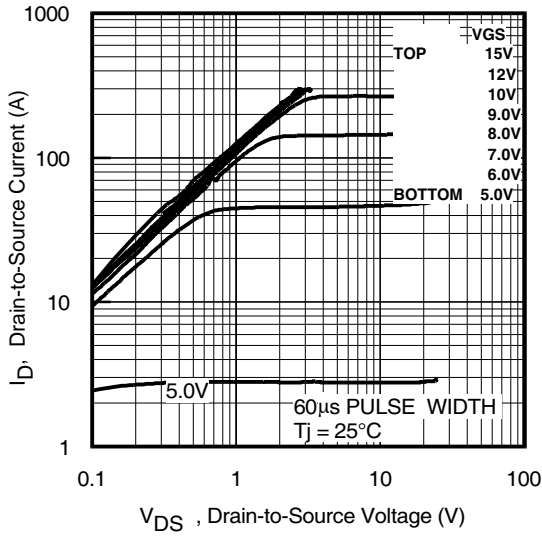


Fig 1. Typical Output Characteristics

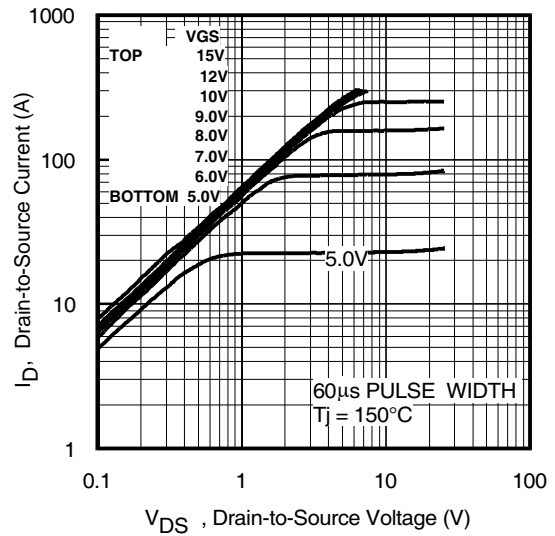


Fig 2. Typical Output Characteristics

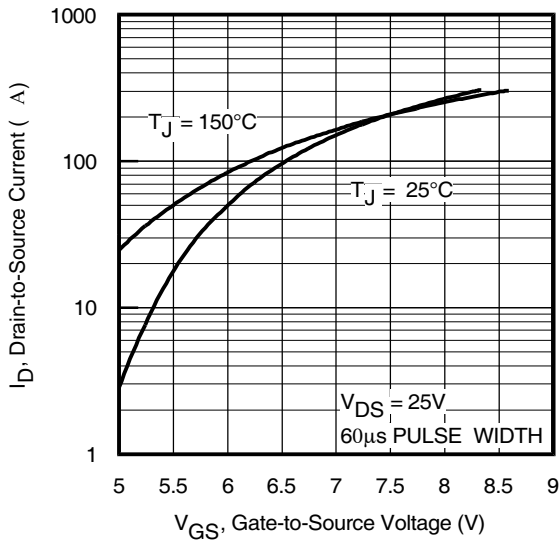


Fig 3. Typical Transfer Characteristics

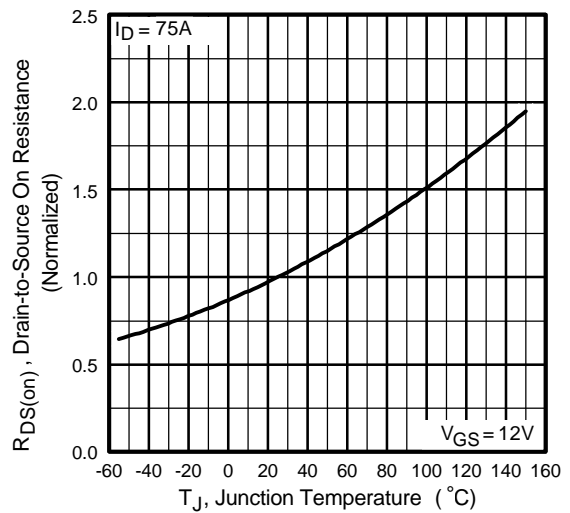


Fig 4. Normalized On-Resistance Vs. Temperature

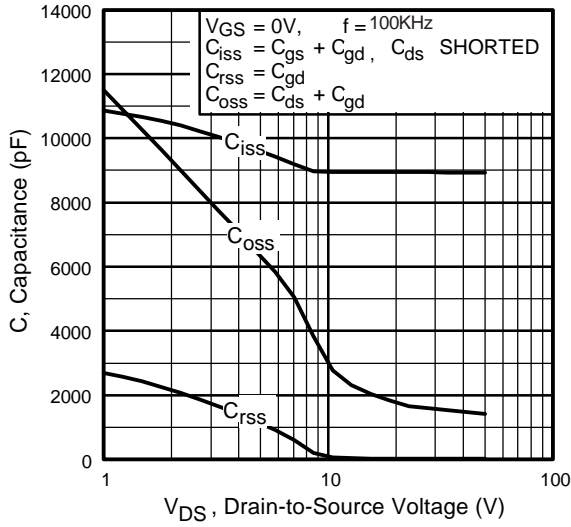


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

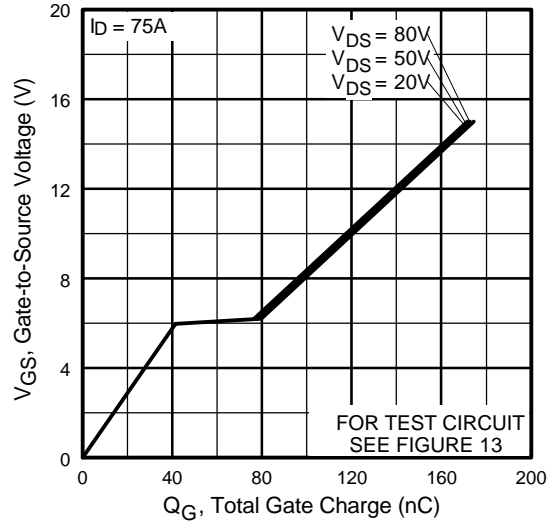


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

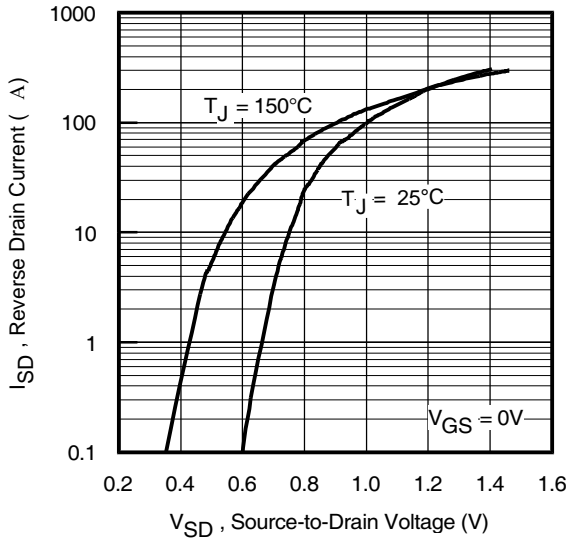


Fig 7. Typical Source-Drain Diode Forward Voltage

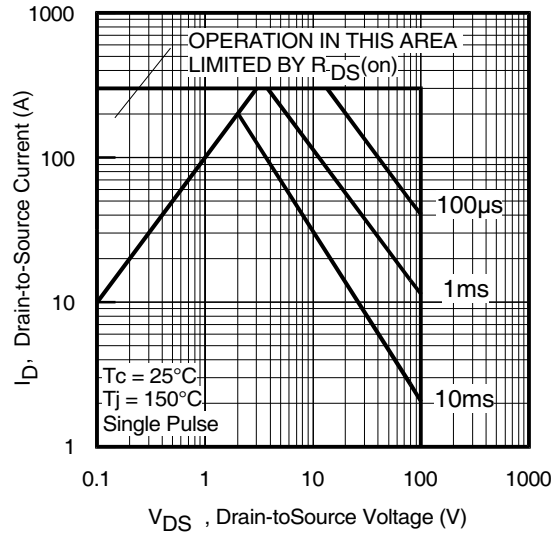


Fig 8. Maximum Safe Operating Area

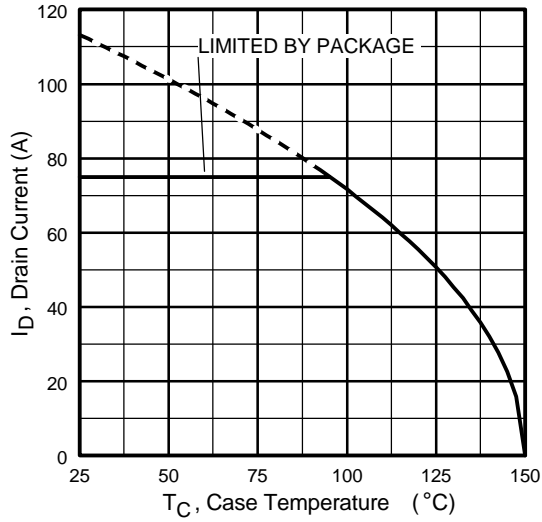


Fig 9. Maximum Drain Current Vs. Case Temperature

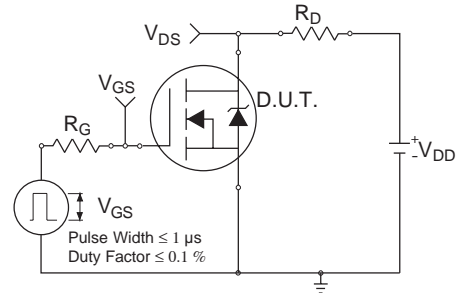


Fig 10a. Switching Time Test Circuit

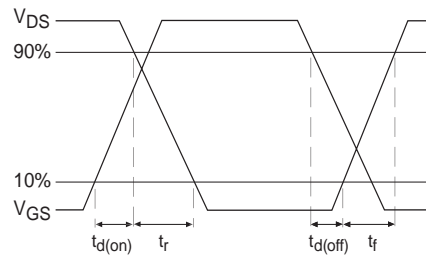


Fig 10b. Switching Time Waveforms

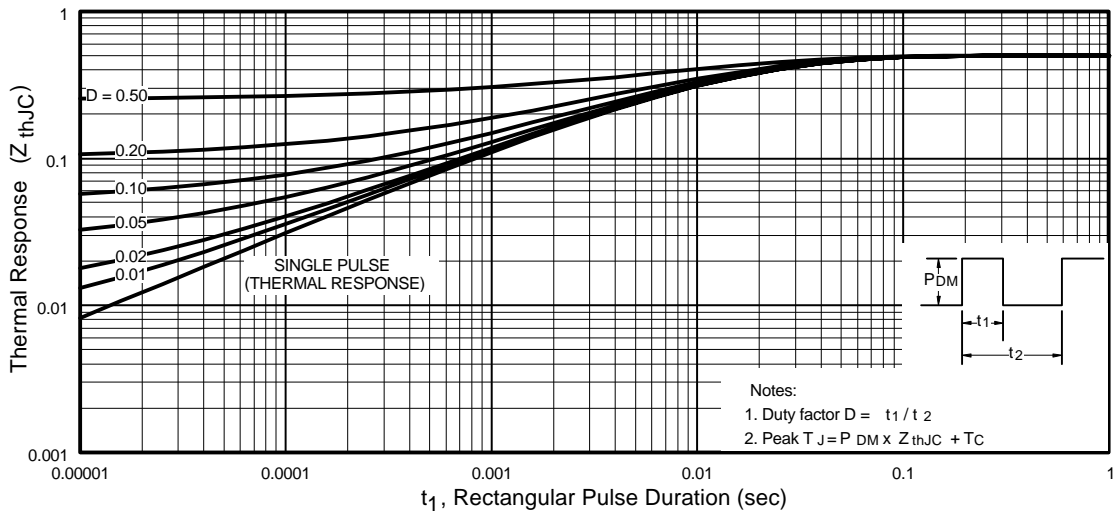


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

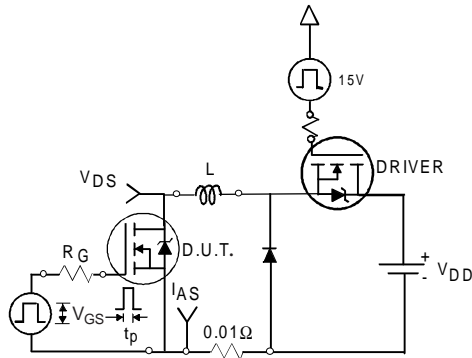


Fig 12a. Unclamped Inductive Test Circuit

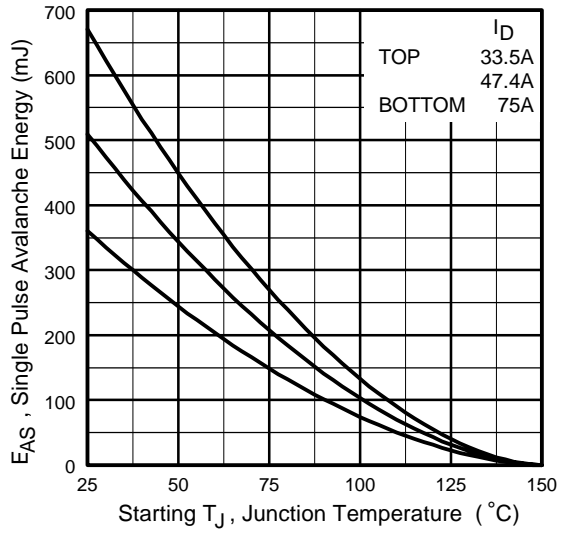


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

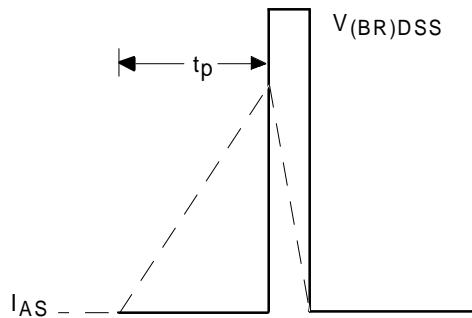


Fig 12b. Unclamped Inductive Waveforms

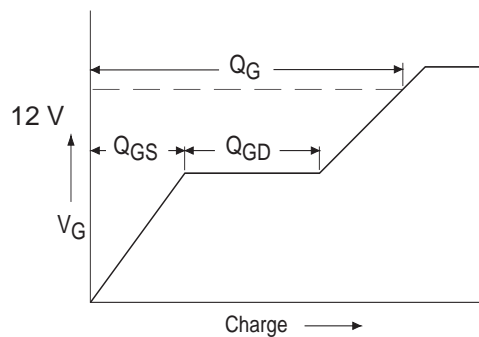


Fig 13a. Basic Gate Charge Waveform

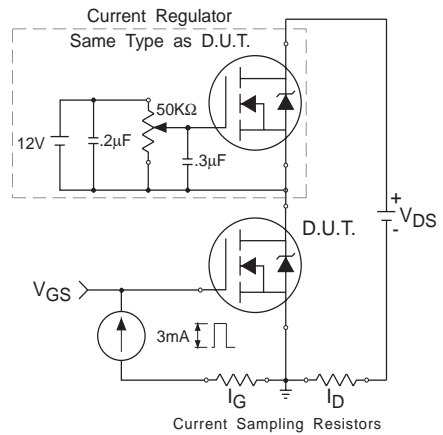
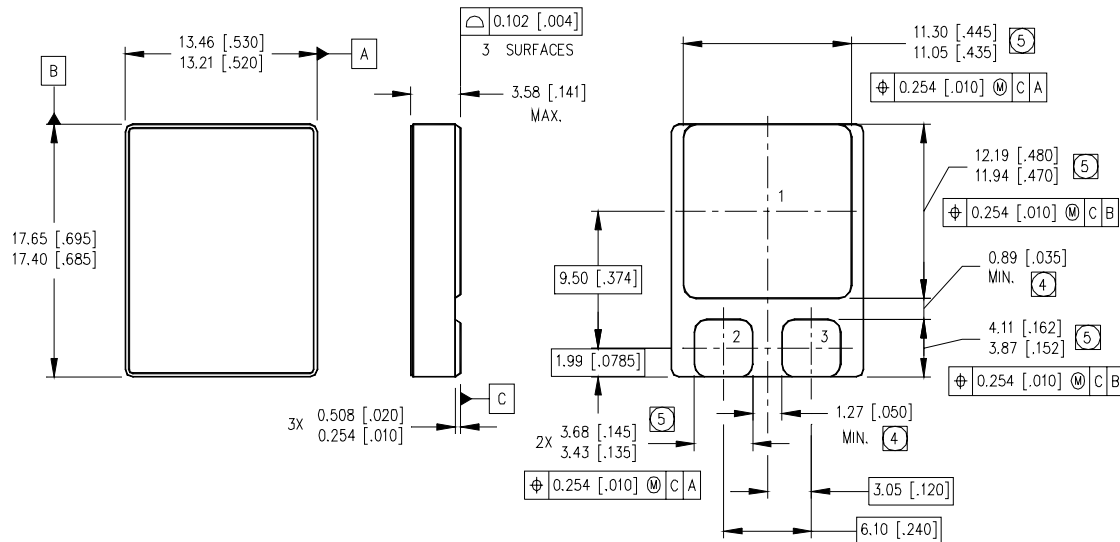


Fig 13b. Gate Charge Test Circuit

Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ② $V_{DD} = 25V$, starting $T_J = 25^\circ C$, $L = 0.13\text{ mH}$
Peak $I_L = 75A$, $V_{GS} = 12V$
- ③ $ISD \leq 75A$, $di/dt \leq 470A/\mu s$,
 $V_{DD} \leq 100V$, $T_J \leq 150^\circ C$
- ④ Pulse width $\leq 300\ \mu s$; Duty Cycle $\leq 2\%$
- ⑤ **Total Dose Irradiation with V_{GS} Bias.**
12 volt V_{GS} applied and $V_{DS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with V_{DS} Bias.**
80 volt V_{DS} applied and $V_{GS} = 0$ during irradiation per MIL-STD-750, method 1019, condition A.

Case Outline and Dimensions — SMD-2



NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- ④ DIMENSION INCLUDES METALLIZATION FLASH.
- ⑤ DIMENSION DOES NOT INCLUDE METALLIZATION FLASH.

PAD ASSIGNMENTS

- 1 = DRAIN
- 2 = GATE
- 3 = SOURCE



IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
IR LEOMINSTER : 205 Crawford St., Leominster, Massachusetts 01453, USA Tel: (978) 534-5776
 TAC Fax: (310) 252-7903

Visit us at www.irf.com for sales contact information.
 Data and specifications subject to change without notice. 08/03